



BSI Standards Publication

Process management for avionics – Aerospace and defence electronic systems containing lead-free solder

Part 4: Ball grid array (BGA) re-balling

National foreword

This Published Document is the UK implementation of IEC TS 62647-4:2018.

The UK participation in its preparation was entrusted to Technical Committee GEL/107, Process management for avionics.

A list of organizations represented on this committee can be obtained on request to its secretary.

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Published by BSI Standards Limited 2018

ISBN 978 0 580 97334 5

ICS 03.100.50; 49.060; 31.020

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This Published Document was published under the authority of the Standards Policy and Strategy Committee on 30 April 2018.

Amendments/corrigenda issued since publication

Date	Text affected
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